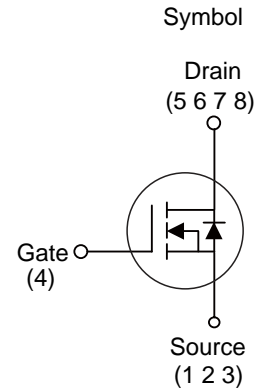


■ PRODUCT CHARACTERISTICS

V _{DSS}	30V
R _{DS(ON)} Typ(@V _{GS} =10V)	4.7mΩ
R _{DS(ON)} Typ(@V _{GS} =4.5V)	6.2mΩ
I _D	20A

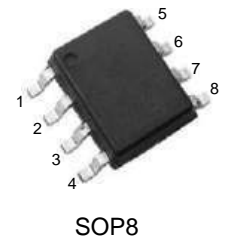


■ APPLICATIONS

- * Electronic lamp ballasts based on half bridge
- * Load Switching, Quick/Wireless Charge.
- * Motor Driving

■ FEATURE

- * Low Gate Charge
- * Pb-Free Lead Plating



■ ORDER INFORMATION

Order Codes		Package	Packing
Halogen-Free	Halogen		
N/A	MOT3145S	SOP8	4000 pieces/Reel

■ ABSOLUTE MAXIMUM RATINGS(T_A=25°C, unless otherwise specified)

Parameter	Symbol	Ratings	Unit
Drain-Source Voltage	V _{DSS}	30	V
Gate-Source Voltage	V _{GSS}	±20	V
Drain Current Continuous(@V _{GS} =10V, T _A =25°C)	I _D	20	A
Drain Current Pulsed	I _{DM}	80	A
Avalanche Energy	E _{AS}	240	mJ
Power Dissipation	P _D	4	W
Junction Temperature	T _J	+150	°C
Storage Temperature	T _{STG}	-55~ +150	°C

■ THERMAL CHARACTERISTICS

Parameter	Symbol	Typ	Unit
Junction to Ambient	R _{thJA}	31.3	°C/W

■ ELECTRICAL CHARACTERISTICS ($T_C=25^{\circ}\text{C}$, unless otherwise noted)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Off characteristics						
Drain to Source Breakdown Voltage	V_{DS}	$V_{GS}=0\text{V}, I_D=250\mu\text{A}$	30	-	-	V
Drain to Source Leakage Current	I_{DSS}	$V_{DS}=30\text{V}, V_{GS}=0\text{V}$	-	-	1	μA
Gate to Source Forward Leakage	$I_{GSS(F)}$	$V_{GS}=+20\text{V}, V_{DS}=0\text{V}$	-	-	100	nA
Gate to Source Reverse Leakage	$I_{GSS(R)}$	$V_{GS}=-20\text{V}, V_{DS}=0\text{V}$	-	-	-100	nA
On characteristics						
Drain to Source On-Resistance	$R_{DS(ON)}$	$V_{GS}=10\text{V}, I_D=10\text{A}$	-	4.7	6	m Ω
		$V_{GS}=4.5\text{V}, I_D=10\text{A}$	-	6.2	7.5	m Ω
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	1	1.5	2.5	V
Dynamic characteristics						
Gate capacitance	R_g	$V_{GS}=0\text{V}, V_{DS}=0\text{V}, f=1.0\text{MHz}$	-	1.6	-	Ω
Forward Transconductance	g_{fs}	$V_{DS}=5\text{V}, I_D=5\text{A}$	-	16	-	S
Input Capacitance	C_{iss}	$V_{DS}=20\text{V}, V_{GS}=0\text{V}$ $f=1.0\text{MHz}$	-	2900	-	pF
Output Capacitance	C_{oss}		-	301	-	pF
Reverse Transfer Capacitance	C_{rss}		-	274	-	pF
Resistive Switching Characteristics						
Turn-on Delay Time	$t_{d(ON)}$	$V_{GS}=10\text{V}, V_{DS}=15\text{V},$ $I_D=10\text{A}, R_G=3\Omega$	-	21	-	ns
Rise Time	t_r		-	32	-	ns
Turn-off Delay Time	$t_{d(OFF)}$		-	59	-	ns
Fall Time	t_f		-	34	-	ns
Total Gate Charge	Q_g	$I_D=10\text{A}, V_{DS}=15\text{V}$ $V_{GS}=10\text{V}$	-	45	-	nC
Gate to Source Charge	Q_{gs}		-	3	-	nC
Gate to Drain("Miller") Charge	Q_{gd}		-	15	-	nC
Source-Drain Diode Characteristics						
Continuous Source Current(Body Diode)	I_S		-	-	20	A
Maximum Pulsed Current(Body Diode)	I_{SM}		-	-	80	A
Diode Forward Voltage	V_{SD}	$I_{SD}=1\text{A}, V_{GS}=0\text{V}$	-	0.72	1.2	V
Reverse Recovery Time	t_{rr}	$I_{SD}=10\text{A}, T_J=25^{\circ}\text{C}$ $di/dt=100\text{A}/\mu\text{s}$	-	15	-	ns
Reverse Recovery Charge	Q_{rr}		-	4	-	nC

■ TYPICAL CHARACTERISTICS

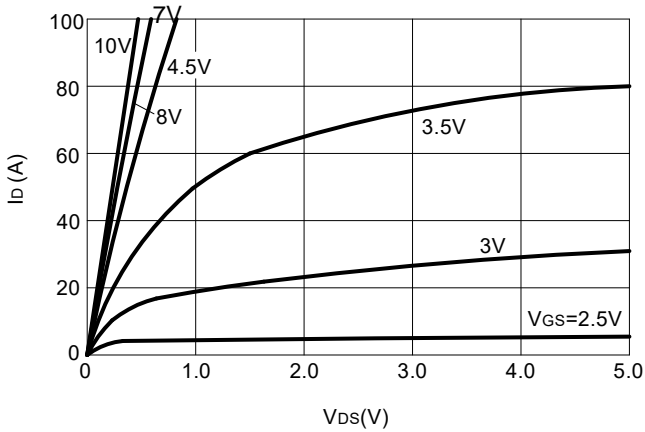


Figure 1: Output Characteristics

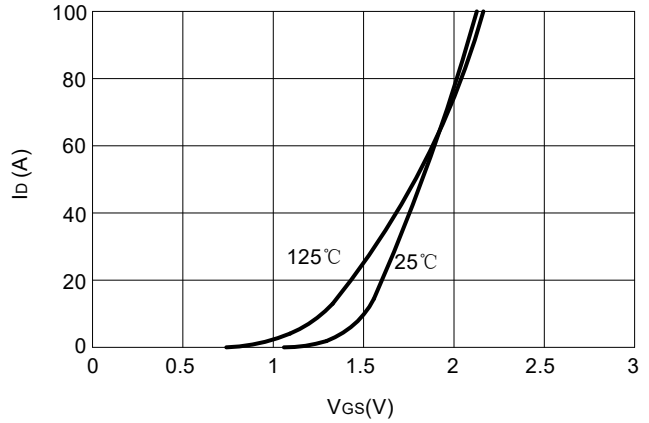


Figure 2: Typical Transfer Characteristics

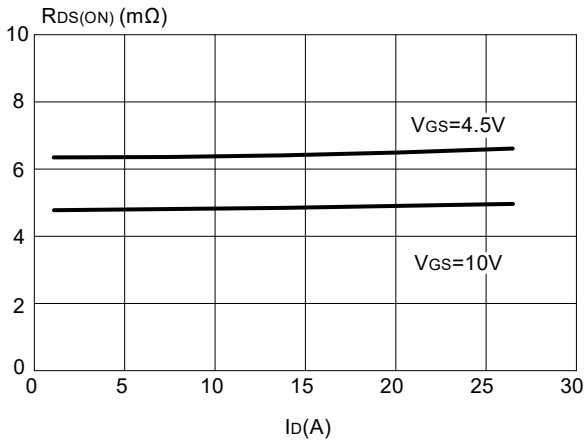


Figure 3: On-resistance vs. Drain Current

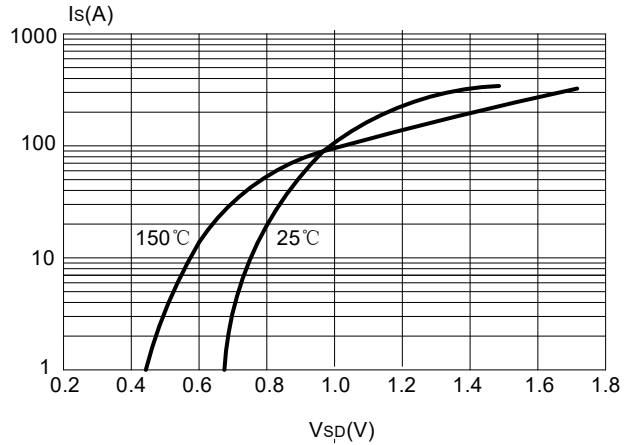


Figure 4: Body Diode Characteristics

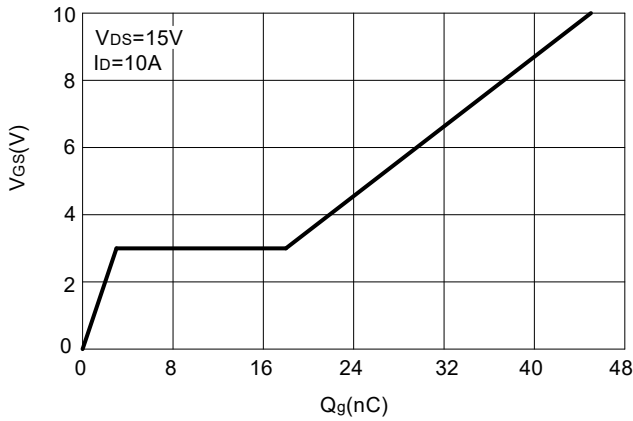


Figure 5: Gate Charge Characteristics

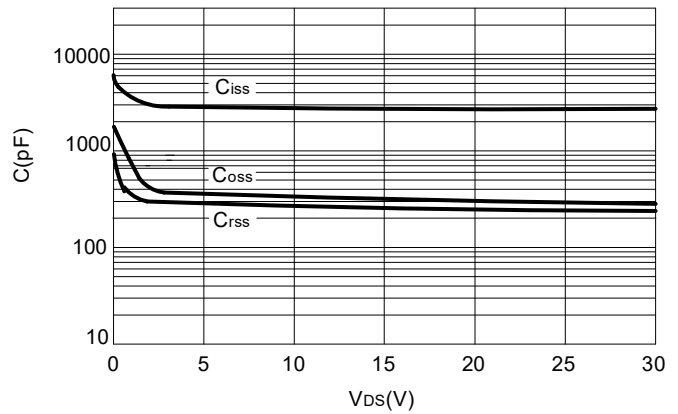


Figure 6: Capacitance Characteristics

■ TYPICAL CHARACTERISTICS(Cont.)

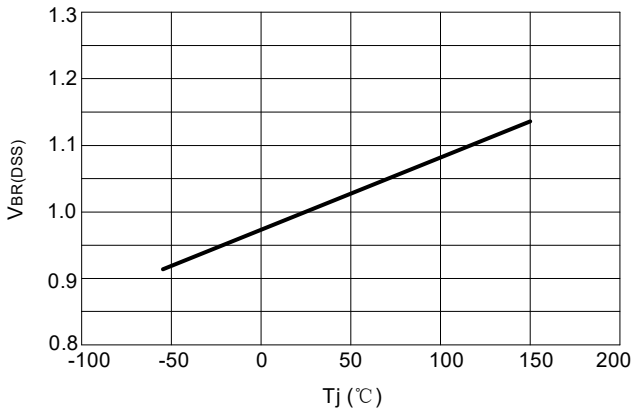


Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

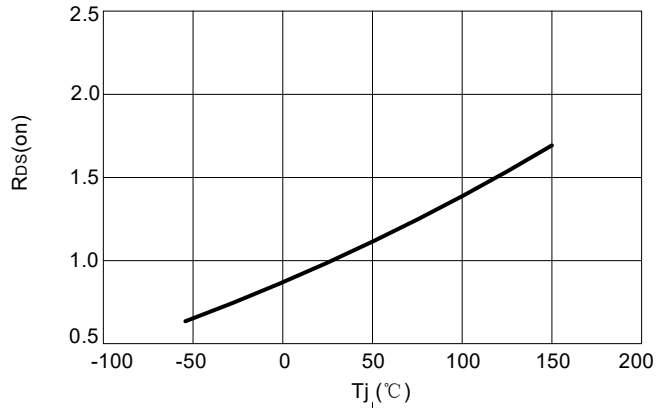


Figure 8: Normalized on Resistance vs. Junction Temperature

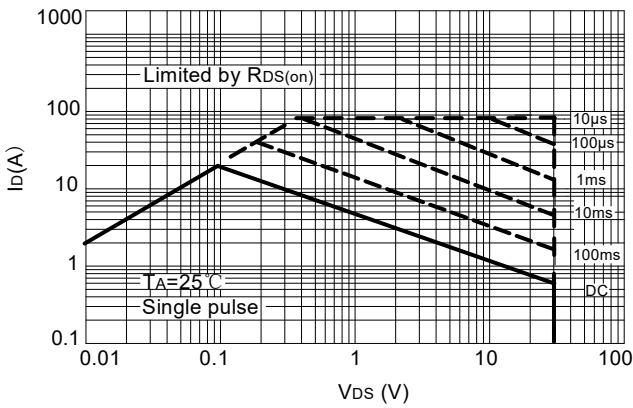


Figure 9: Maximum Safe Operating Area

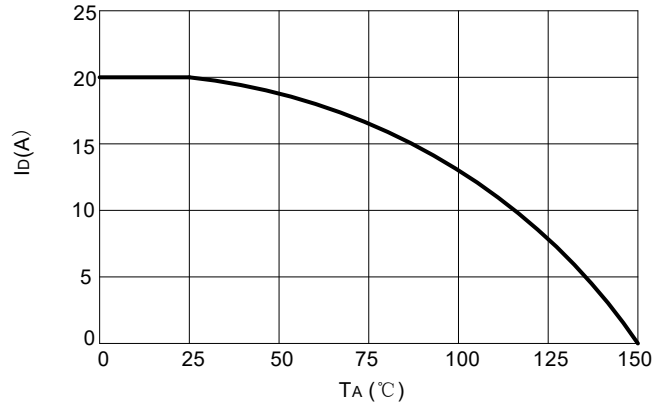


Figure 10: Maximum Continuous Drain Current vs. Ambient Temperature

■ SOP8 PACKAGE OUTLINE DIMENSIONS

